查询BC847CWT1供应商 捷多邦，专业PCB打样工厂，24小时加急出货

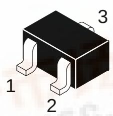
MOTOROLA
SEMICONDUCTOR TECHNICAL DATA

Order this document
by BC846AWT1/D

General Purpose Transistors
NPN Silicon

BC846AWT1,BWT1
BC847AWT1,BWT1,CWT1
BC848AWT1,BWT1,CWT1

These transistors are designed for general purpose amplifier applications. They are housed in the SOT–323/SC–70 which is designed for low power surface mount applications.



CASE 419–02, STYLE 3
SOT–323/SC–70

MAXIMUM RATINGS

Rating	Symbol	BC846	BC847	BC848	Unit
Collector–Emitter Voltage	V_{CEO}	65	45	30	V
Collector–Base Voltage	V_{CBO}	80	50	30	V
Emitter–Base Voltage	V_{EBO}	6.0	6.0	5.0	V
Collector Current — Continuous	I_C	100	100	100	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR–5 Board, (1) T_A = 25°C	P_D	150	mW
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	833	°C/W
Total Device Dissipation	P_D	2.4	mW/°C
Junction and Storage Temperature	T_J, T_{stg}	–55 to +150	°C

DEVICE MARKING

BC846AWT1 = 1A; BC846BWT1 = 1B; BC847AWT1 = 1E; BC847BWT1 = 1F;
BC847CWT1 = 1G; BC848AWT1 = 1J; BC848BWT1 = 1K; BC848CWT1 = 1L

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Collector–Emitter Breakdown Voltage (I_C = 10 mA)	BC846 Series BC847 Series BC848 Series	$V_{(BR)CEO}$	65 45 30	— — —	— — —	V
Collector–Emitter Breakdown Voltage (I_C = 10 µA, V_{EB} = 0)	BC846 Series BC847 Series BC848 Series	$V_{(BR)CES}$	80 50 30	— — —	— — —	V
Collector–Base Breakdown Voltage (I_C = 10 µA)	BC846 Series BC847 Series BC848 Series	$V_{(BR)CBO}$	80 50 30	— — —	— — —	V
Emitter–Base Breakdown Voltage (I_E = 1.0 µA)	BC846 Series BC847 Series BC848 Series	$V_{(BR)EBO}$	6.0 6.0 5.0	— — —	— — —	V
Collector Cutoff Current (V_{CB} = 30 V) (V_{CB} = 30 V, T_A = 150°C)		I_{CBO}	— —	— —	15 5.0	nA µA

1. FR–5 = 1.0 x 0.75 x 0.062 in

Thermal Clad is a trademark of the Bergquist Company.

找PDF 维库一下 pdf.dzsc.com

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted) (Continued)

Characteristic	Symbol	Min	Typ	Max	Unit
ON CHARACTERISTICS					
DC Current Gain (I_C = 10 µA, V_{CE} = 5.0 V) BC846A, BC847A, BC848A	h_{FE}	—	90	—	—
BC846B, BC847B, BC848B		—	150	—	
BC847C, BC848C		—	270	—	
(I_C = 2.0 mA, V_{CE} = 5.0 V) BC846A, BC847A, BC848A		110	180	220	
BC846B, BC847B, BC848B		200	290	450	
BC847C, BC848C		420	520	800	
Collector–Emitter Saturation Voltage (I_C = 10 mA, I_B = 0.5 mA)	$V_{CE(sat)}$	—	—	0.25	V
(I_C = 100 mA, I_B = 5.0 mA)		—	—	0.6	
Base–Emitter Saturation Voltage (I_C = 10 mA, I_B = 0.5 mA)	$V_{BE(sat)}$	—	0.7	—	V
(I_C = 100 mA, I_B = 5.0 mA)		—	0.9	—	
Base–Emitter Voltage (I_C = 2.0 mA, V_{CE} = 5.0 V)	$V_{BE(on)}$	580	660	700	mV
(I_C = 10 mA, V_{CE} = 5.0 V)		—	—	770	
SMALL–SIGNAL CHARACTERISTICS					
Current–Gain — Bandwidth Product (I_C = 10 mA, V_{CE} = 5.0 Vdc, f = 100 MHz)	f_T	100	—	—	MHz
Output Capacitance (V_{CB} = 10 V, f = 1.0 MHz)	C_{obo}	—	—	4.5	pF
Noise Figure (I_C = 0.2 mA, V_{CE} = 5.0 Vdc, R_S = 2.0 kΩ, f = 1.0 kHz, BW = 200 Hz) BC846A, BC847A, BC848A	NF				dB
BC846B, BC847B, BC848B		—	—	10	
BC847C, BC848C		—	—	4.0	

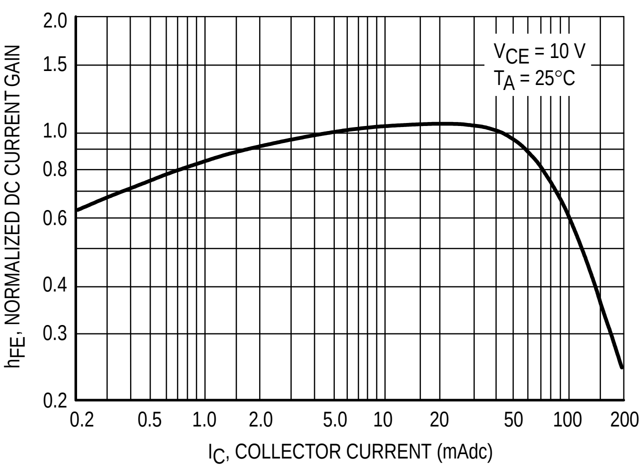


Figure 1. Normalized DC Current Gain

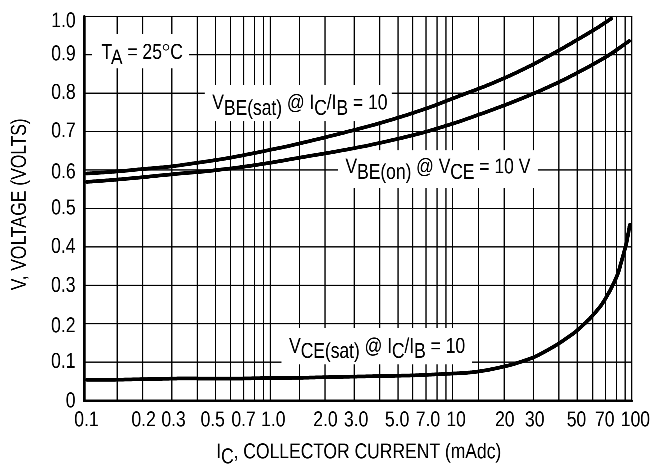


Figure 2. "Saturation" and "On" Voltages

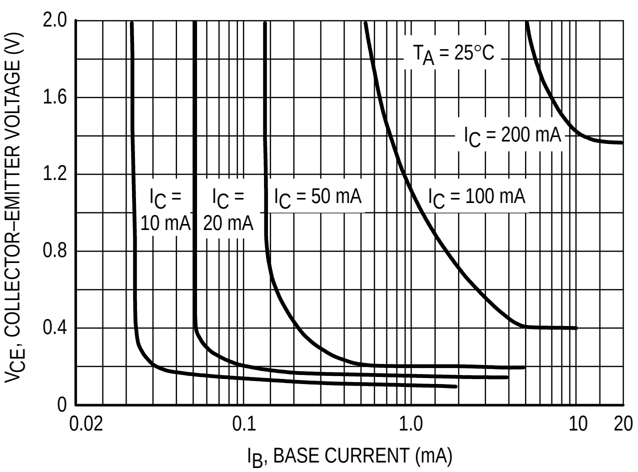


Figure 3. Collector Saturation Region

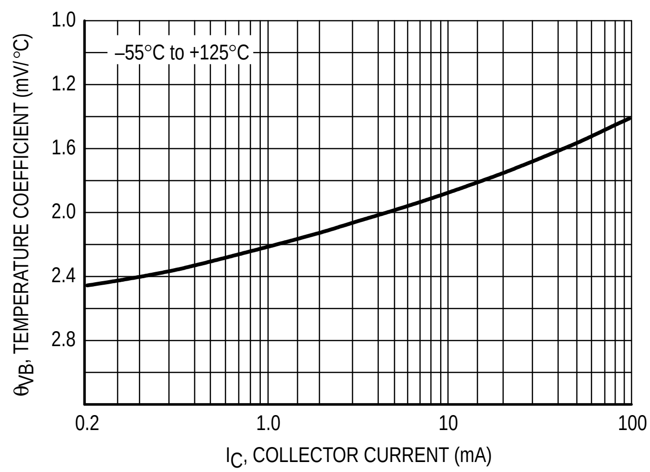


Figure 4. Base–Emitter Temperature Coefficient

BC847/BC848

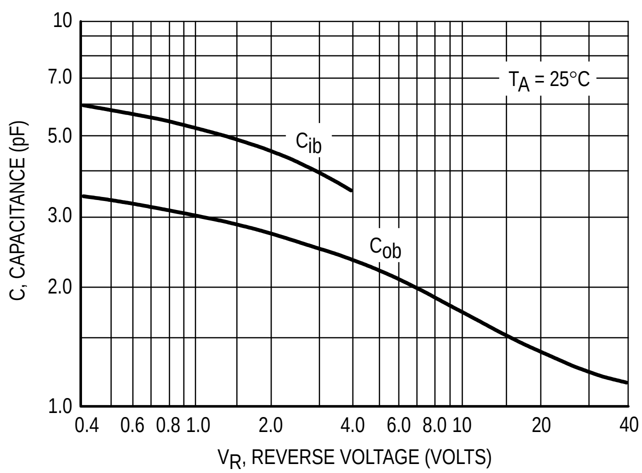


Figure 5. Capacitances

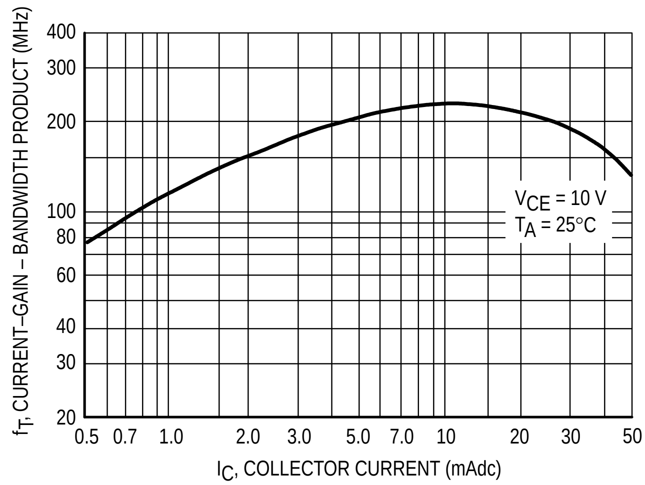


Figure 6. Current–Gain – Bandwidth Product

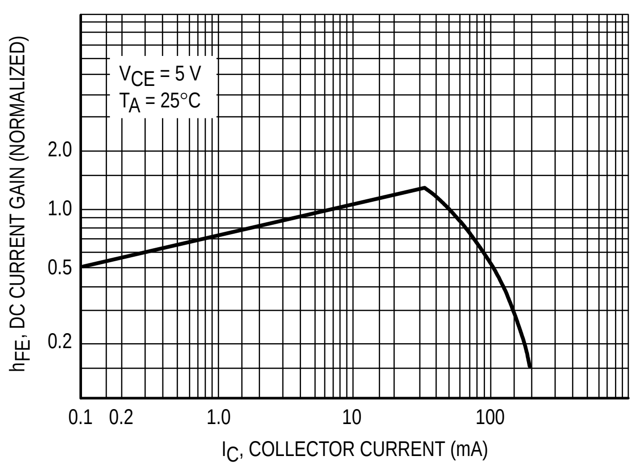


Figure 7. DC Current Gain

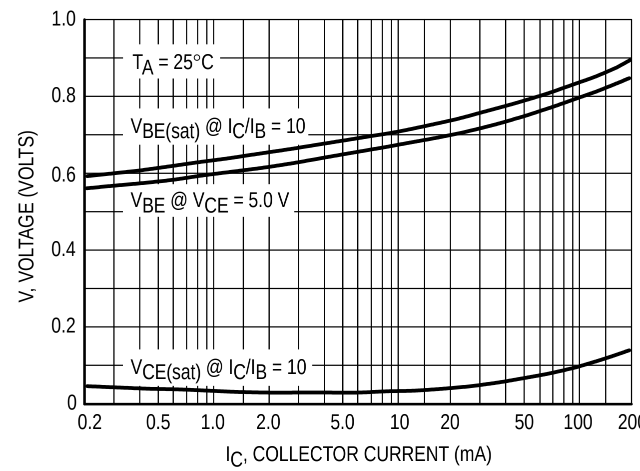


Figure 8. “On” Voltage

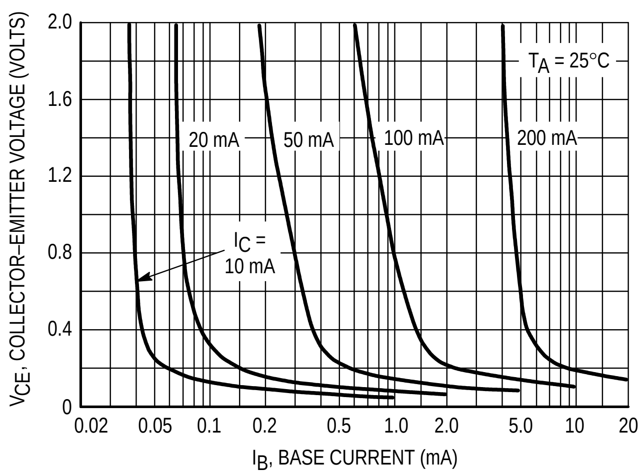


Figure 9. Collector Saturation Region

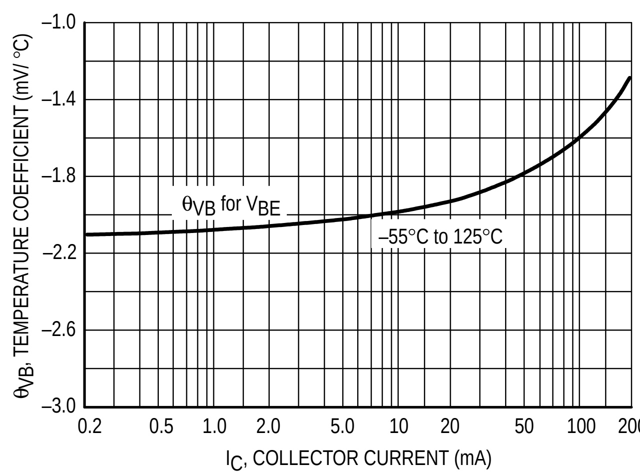


Figure 10. Base–Emitter Temperature Coefficient

BC846

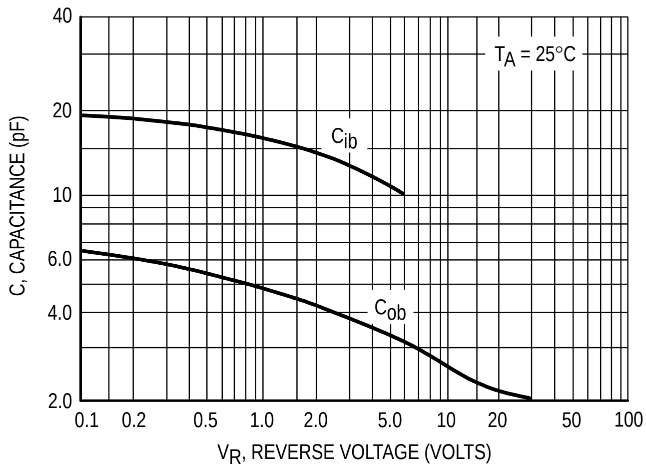


Figure 11. Capacitance

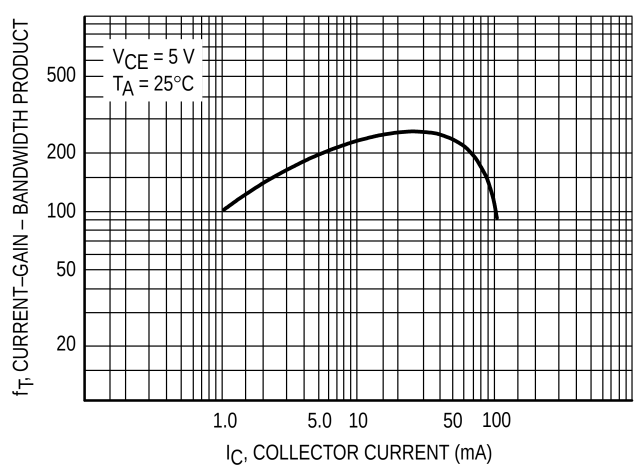
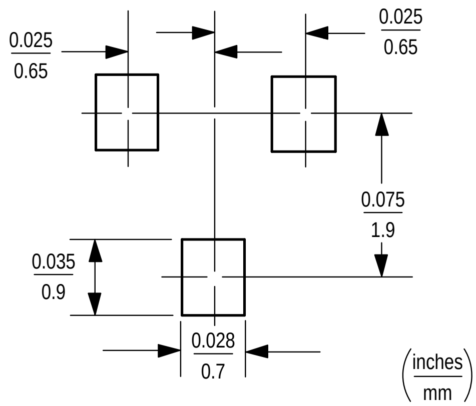


Figure 12. Current–Gain – Bandwidth Product

INFORMATION FOR USING THE SOT–323/SC–70 SURFACE MOUNT PACKAGE

MINIMUM RECOMMENDED FOOTPRINT FOR SURFACE MOUNTED APPLICATIONS

Surface mount board layout is a critical portion of the total design. The footprint for the semiconductor packages must be the correct size to insure proper solder connection interface between the board and the package. With the correct pad geometry, the packages will self align when subjected to a solder reflow process.



SOT–323/SC–70

SOT–323/SC–70 POWER DISSIPATION

The power dissipation of the SOT–323/SC–70 is a function of the pad size. This can vary from the minimum pad size for soldering to a pad size given for maximum power dissipation. Power dissipation for a surface mount device is determined by $T_{J(max)}$, the maximum rated junction temperature of the die, $R_{\theta JA}$, the thermal resistance from the device junction to ambient, and the operating temperature, T_A. Using the values provided on the data sheet for the SOT–323/SC–70 package, P_D can be calculated as follows:

$$P_D = \frac{T_{J(max)} - T_A}{R_{\theta JA}}$$

The values for the equation are found in the maximum ratings table on the data sheet. Substituting these values into the equation for an ambient temperature T_A of 25°C, one can calculate the power dissipation of the device which in this case is 150 milliwatts.

$$P_D = \frac{150°C - 25°C}{833°C/W} = 150 \text{ milliwatts}$$

The 833°C/W for the SOT–323/SC–70 package assumes the use of the recommended footprint on a glass epoxy printed circuit board to achieve a power dissipation of 150 milliwatts. There are other alternatives to achieving higher power dissipation from the SOT–323/SC–70 package. Another alternative would be to use a ceramic substrate or an aluminum core board such as Thermal Clad™. Using a board material such as Thermal Clad, an aluminum core board, the power dissipation can be doubled using the same footprint.

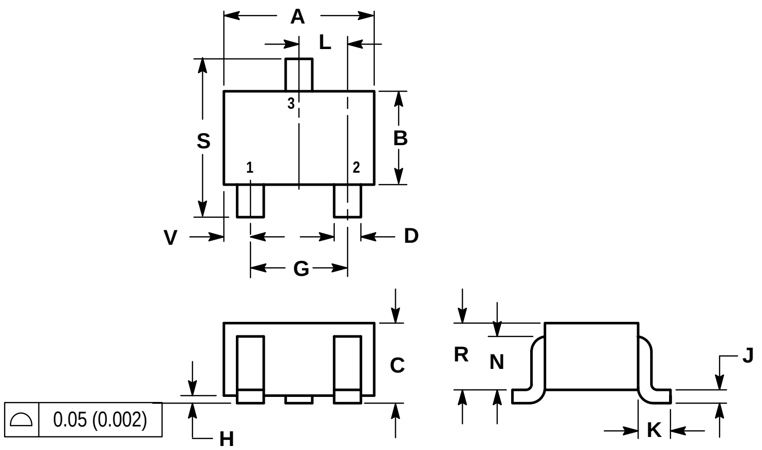
SOLDERING PRECAUTIONS

The melting temperature of solder is higher than the rated temperature of the device. When the entire device is heated to a high temperature, failure to complete soldering within a short time could result in device failure. Therefore, the following items should always be observed in order to minimize the thermal stress to which the devices are subjected.

- Always preheat the device.
- The delta temperature between the preheat and soldering should be 100°C or less.*
- When preheating and soldering, the temperature of the leads and the case must not exceed the maximum temperature ratings as shown on the data sheet. When using infrared heating with the reflow soldering method, the difference shall be a maximum of 10°C.
- The soldering temperature and time shall not exceed 260°C for more than 10 seconds.
- When shifting from preheating to soldering, the maximum temperature gradient shall be 5°C or less.
- After soldering has been completed, the device should be allowed to cool naturally for at least three minutes. Gradual cooling should be used as the use of forced cooling will increase the temperature gradient and result in latent failure due to mechanical stress.
- Mechanical stress or shock should not be applied during cooling.

* Soldering a device without preheating can cause excessive thermal shock and stress which can result in damage to the device.

PACKAGE DIMENSIONS



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	0.071	0.087	1.80	2.20
B	0.045	0.053	1.15	1.35
C	0.035	0.049	0.90	1.25
D	0.012	0.016	0.30	0.40
G	0.047	0.055	1.20	1.40
H	0.000	0.004	0.00	0.10
J	0.004	0.010	0.10	0.25
K	0.017 REF		0.425 REF	
L	0.026 BSC		0.650 BSC	
N	0.028 REF		0.700 REF	
R	0.031	0.039	0.80	1.00
S	0.079	0.087	2.00	2.20
V	0.012	0.016	0.30	0.40

STYLE 3:
PIN 1. BASE
2. EMITTER
3. COLLECTOR

CASE 419–02
ISSUE G
SOT–323/SC–70

Motorola reserves the right to make changes without further notice to any products herein. Motorola makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Motorola assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters can and do vary in different applications. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. Motorola does not convey any license under its patent rights nor the rights of others. Motorola products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Motorola product could create a situation where personal injury or death may occur. Should Buyer purchase or use Motorola products for any such unintended or unauthorized application, Buyer shall indemnify and hold Motorola and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Motorola was negligent regarding the design or manufacture of the part. Motorola and Ⓜ are registered trademarks of Motorola, Inc. Motorola, Inc. is an Equal Opportunity/Affirmative Action Employer.

How to reach us:
USA/EUROPE: Motorola Literature Distribution;
P.O. Box 20912; Phoenix, Arizona 85036. 1–800–441–2447

MFAX: RMFAX0@email.sps.mot.com – TOUCHTONE (602) 244–6609
INTERNET: http://Design–NET.com

JAPAN: Nippon Motorola Ltd.; Tatsumi–SPD–JLDC, Toshikatsu Otsuki,
6F Seibu–Butsuryu–Center, 3–14–2 Tatsumi Koto–Ku, Tokyo 135, Japan. 03–3521–8315

HONG KONG: Motorola Semiconductors H.K. Ltd.; 8B Tai Ping Industrial Park,
51 Ting Kok Road, Tai Po, N.T., Hong Kong. 852–26629298